

Title (en)  
GALVANIZING PROCESS

Publication  
**EP 0183034 B1 19900711 (DE)**

Application  
**EP 85113105 A 19851016**

Priority  
DE 3439750 A 19841031

Abstract (en)  
[origin: US4721554A] In a method for high-speed electrolytic-deposition of metallic layers on ribbon or cord-like strips, the strips which are electrically connected to the negative side of an electric DC power source are moved through a hollow guide rail containing an electrolyte solution and past an anode structure arranged within the hollow guide rail and connected to the positive side of the DC power source. An electrolyte solution circulating conduit structure including a circulating pump is connected to opposite ends of the guide rail and, while the metal is deposited on the strip which is moved through the guide rail in one direction, the electrolyte solution is circulated through the guide rail in the opposite direction at a speed which provides for a Reynolds No. of over 80,000 with regard to the relative strip speed in the electrolyte solution so as to provide turbulent flow conditions adjacent the strip surface which greatly increase the electrolyte deposition rates. The hollow guide rail is preferably arranged vertically with the strip moving upwardly and the electrolyte solution flowing downwardly through the guide rail.

IPC 1-7  
**C25D 5/08**; **C25D 7/06**

IPC 8 full level  
**C25D 5/08** (2006.01); **C25D 7/06** (2006.01)

CPC (source: EP US)  
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**EP 0183034 A2 19860604**; **EP 0183034 A3 19871028**; **EP 0183034 B1 19900711**; AT E54474 T1 19900715; DE 3439750 A1 19860430; DE 3439750 C2 19890105; JP S61113790 A 19860531; US 4721554 A 19880126

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**EP 85113105 A 19851016**; AT 85113105 T 19851016; DE 3439750 A 19841031; JP 24178185 A 19851030; US 92681886 A 19861031